# High Speed Infrared Emitting Diodes, 850 nm, Surface Emitter Technology

VSMY2850RGX01

VSMY2850GX01

## LINKS TO ADDITIONAL RESOURCES

Infographics

## DESCRIPTION

As part of the SurfLight™ portfolio, the VSMY2850 series are infrared, 850 nm emitting diodes based on GaAlAs surface emitter chip technology with extreme high radiant intensities, high optical power and high speed, molded in clear, untinted plastic packages (with lens) for surface mounting (SMD).

## FEATURES

- Package type: surface-mount
- Package form: GW, RGW
- Dimensions (L x W x H in mm): 2.3 x 2.3 x 2.8
- AEC-Q101 qualified
- Peak wavelength: $\lambda_p$ = 850 nm
- High reliability
- High radiant power
- Very high radiant intensity
- Angle of half intensity: φ = ± 10°
- Suitable for high pulse current operation
- Terminal configurations: gullwing or reverse gullwing
- Package matches with detector VEMD2500X01 series
- Floor life: 4 weeks, MSL 2a, according to J-STD-020
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

## APPLICATIONS

- Automotive sensors
- Miniature light barrier
- Photointerrupters
- Optical switch
- Emitter source for proximity sensors
- IR illumination
- Head-up displays

| PRODUCT SUMMARY | | | | |
|---|---|---|---|---|
| COMPONENT | $I_e$ (mW/sr) | φ (°) | $\lambda_P$ (nm) | $t_r$ (ns) |
| VSMY2850RGX01 | 125 | ± 10 | 850 | 10 |
| VSMY2850GX01 | 125 | ± 10 | 850 | 10 |

**Note**

- Test conditions see table “Basic Characteristics“

| ORDERING INFORMATION | | | |
|---|---|---|---|
| ORDERING CODE | PACKAGING | REMARKS | PACKAGE FORM |
| VSMY2850RGX01 | Tape and reel | MOQ: 6000 pcs, 6000 pcs/reel | Reverse gullwing |
| VSMY2850GX01 | Tape and reel | MOQ: 6000 pcs, 6000 pcs/reel | Gullwing |

**Note**

- MOQ: minimum order quantity

| **ABSOLUTE MAXIMUM RATINGS** ($T_{amb}$ = 25 °C, unless otherwise specified) | | | | |
|---|---|---|---|---|
| **PARAMETER** | **TEST CONDITION** | **SYMBOL** | **VALUE** | **UNIT** |
| Reverse voltage | | $V_R$ | 5 | V |
| Forward current | | $I_F$ | 100 | mA |
| Peak forward current | $t_p/T$ = 0.5, $t_p$ = 100 µs | $I_{FM}$ | 200 | mA |
| Surge forward current | $t_p$ = 100 µs | $I_{FSM}$ | 1 | A |
| Power dissipation | | $P_V$ | 190 | mW |
| Junction temperature | | $T_j$ | 100 | °C |
| Operating temperature range | | $T_{amb}$ | -40 to +85 | °C |
| Storage temperature range | | $T_{stg}$ | -40 to +100 | °C |
| Soldering temperature | According to Fig. 10, J-STD-020 | $T_{sd}$ | 260 | °C |
| Thermal resistance junction-to-ambient | EIA / JESD51 | $R_{thJA}$ | 250 | K/W |

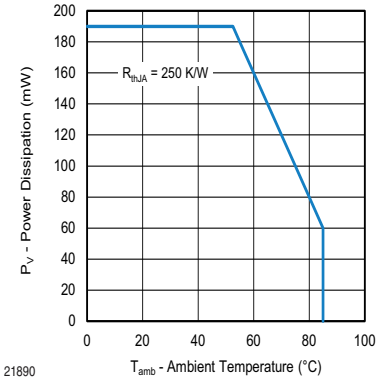



Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

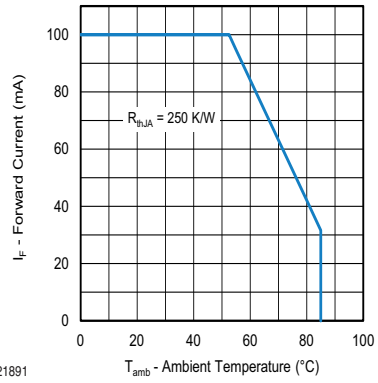



Fig. 2 - Forward Current Limit vs. Ambient Temperature

| **BASIC CHARACTERISTICS** ($T_{amb}$ = 25 °C, unless otherwise specified) | | | | | | |
|---|---|---|---|---|---|---|
| **PARAMETER** | **TEST CONDITION** | **SYMBOL** | **MIN.** | **TYP.** | **MAX.** | **UNIT** |
| Forward voltage | $I_F$ = 100 mA, $t_p$ = 20 ms | $V_F$ | - | 1.6 | 1.9 | V |
| | $I_F$ = 1 A, $t_p$ = 100 µs | $V_F$ | - | 2.8 | - | V |
| Temperature coefficient of $V_F$ | $I_F$ = 100 mA | $TK_{VF}$ | - | -1.5 | - | mV/K |
| Reverse current | | $I_R$ | Not designed for reverse operation | | | µA |
| Junction capacitance | $V_R$ = 0 V, f = 1 MHz, E = 0 mW/cm² | $C_J$ | - | 50 | - | pF |
| Radiant intensity | $I_F$ = 100 mA, $t_p$ = 20 ms | $I_e$ | 70 | 125 | 210 | mW/sr |
| | $I_F$ = 1 A, $t_p$ = 100 µs | $I_e$ | - | 1000 | - | mW/sr |
| Radiant power | $I_F$ = 100 mA, $t_p$ = 20 ms | $\phi_e$ | - | 55 | - | mW |
| Temperature coefficient of radiant power | $I_F$ = 100 mA | $TK\phi_e$ | - | -0.12 | - | %/K |
| Angle of half intensity | | $\varphi$ | - | ± 10 | - | ° |
| Peak wavelength | $I_F$ = 100 mA | $\lambda_p$ | 840 | 850 | 870 | nm |
| Spectral bandwidth | $I_F$ = 30 mA | $\Delta\lambda$ | - | 30 | - | nm |
| Temperature coefficient of $\lambda_p$ | $I_F$ = 30 mA | $TK\lambda_p$ | - | 0.25 | - | nm/K |
| Rise time | $I_F$ = 100 mA, 10 % to 90 % | $t_r$ | - | 10 | - | ns |
| Fall time | $I_F$ = 100 mA, 10 % to 90 % | $t_f$ | - | 10 | - | ns |

**BASIC CHARACTERISTICS** ($T_{amb}$ = 25 °C, unless otherwise specified)

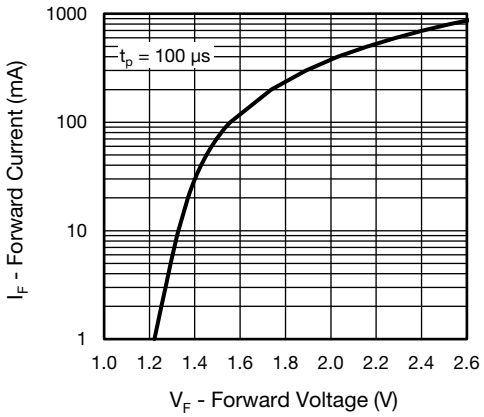



Fig. 3 - Forward Current vs. Forward Voltage

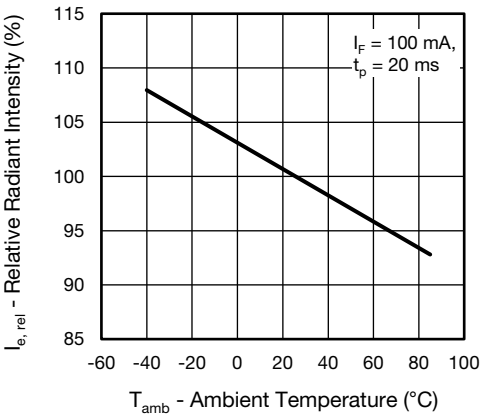



Fig. 6 - Relative Radiant Intensity vs. Ambient Temperature

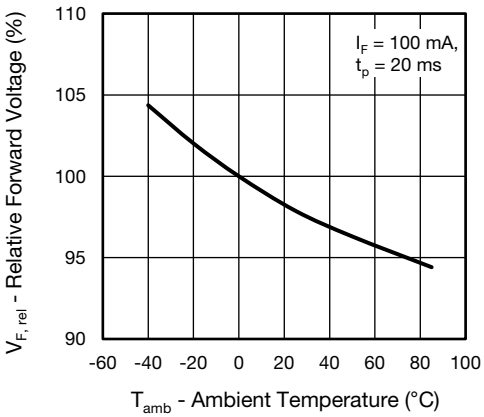



Fig. 4 - Relative Forward Voltage vs. Ambient Temperature

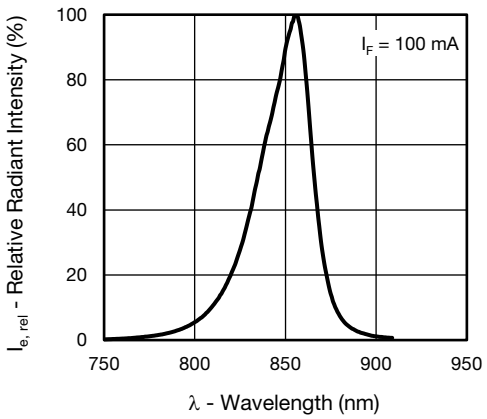



Fig. 7 - Relative Radiant Intensity vs. Wavelength

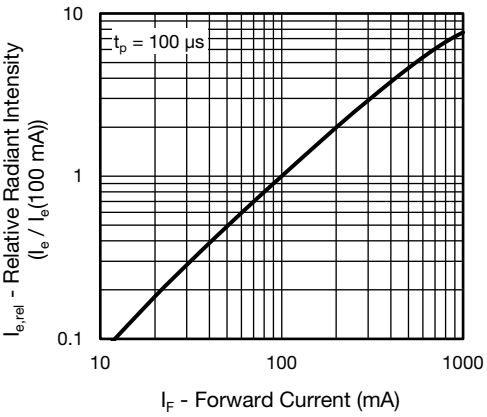



Fig. 5 - Relative Radiant Intensity vs. Forward Current

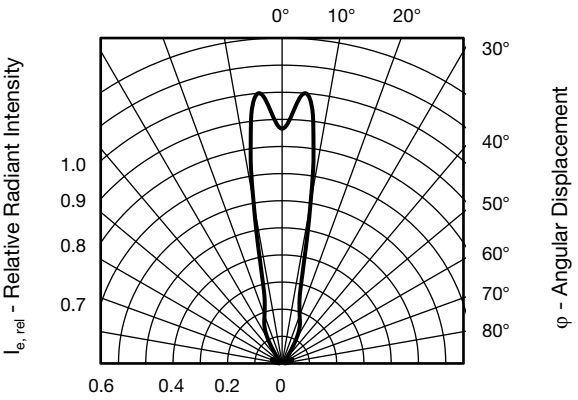



Fig. 8 - Relative Radiant Intensity vs. Angular Displacement

## SOLDER PROFILE

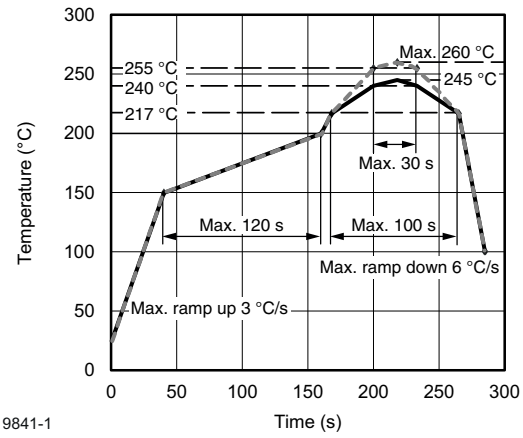



Fig. 9 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020

## DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

## FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

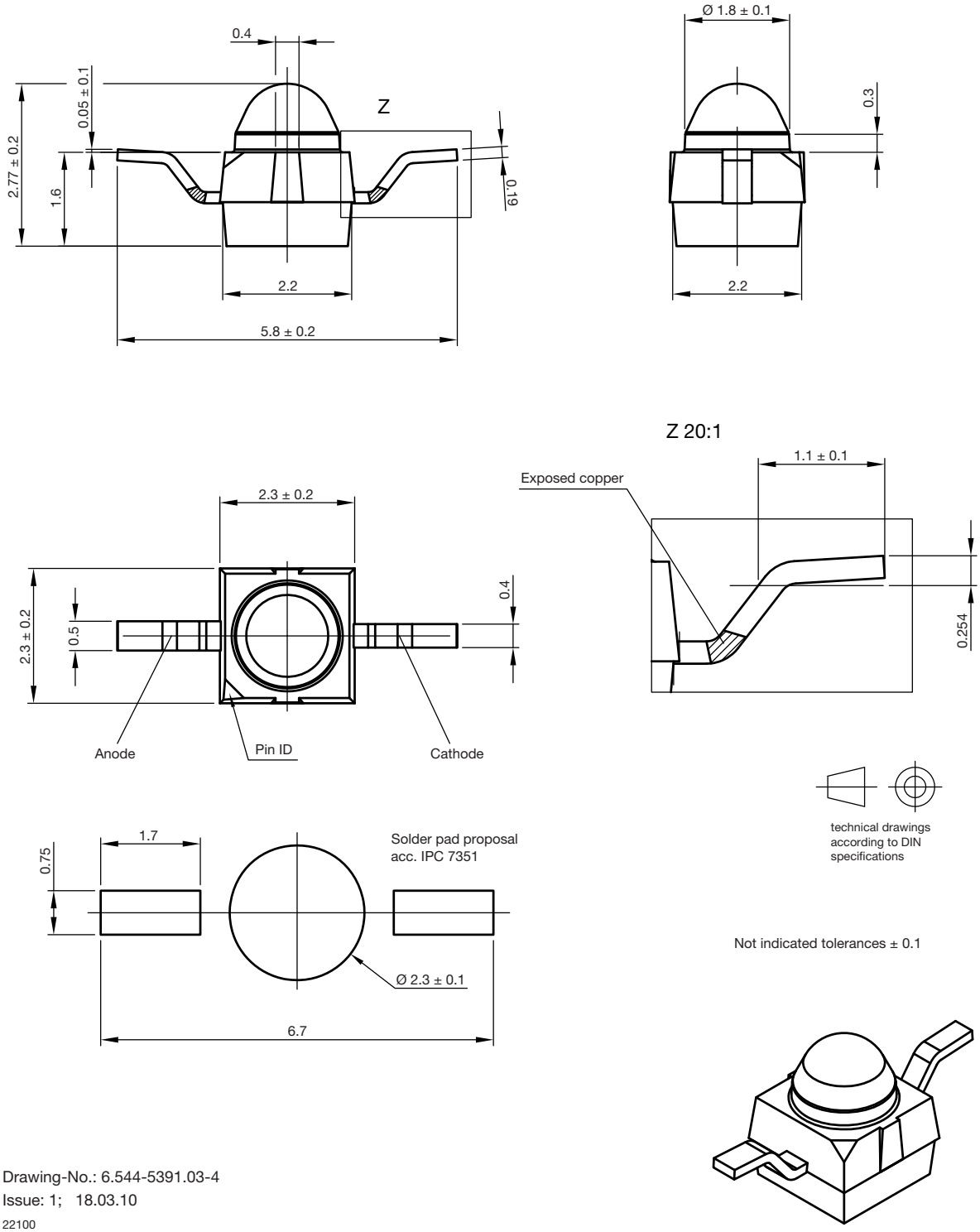
Conditions: $T_{amb}$ < 30 °C, RH < 60 %

Moisture sensitivity level 2a, according to J-STD-020.

## DRYING

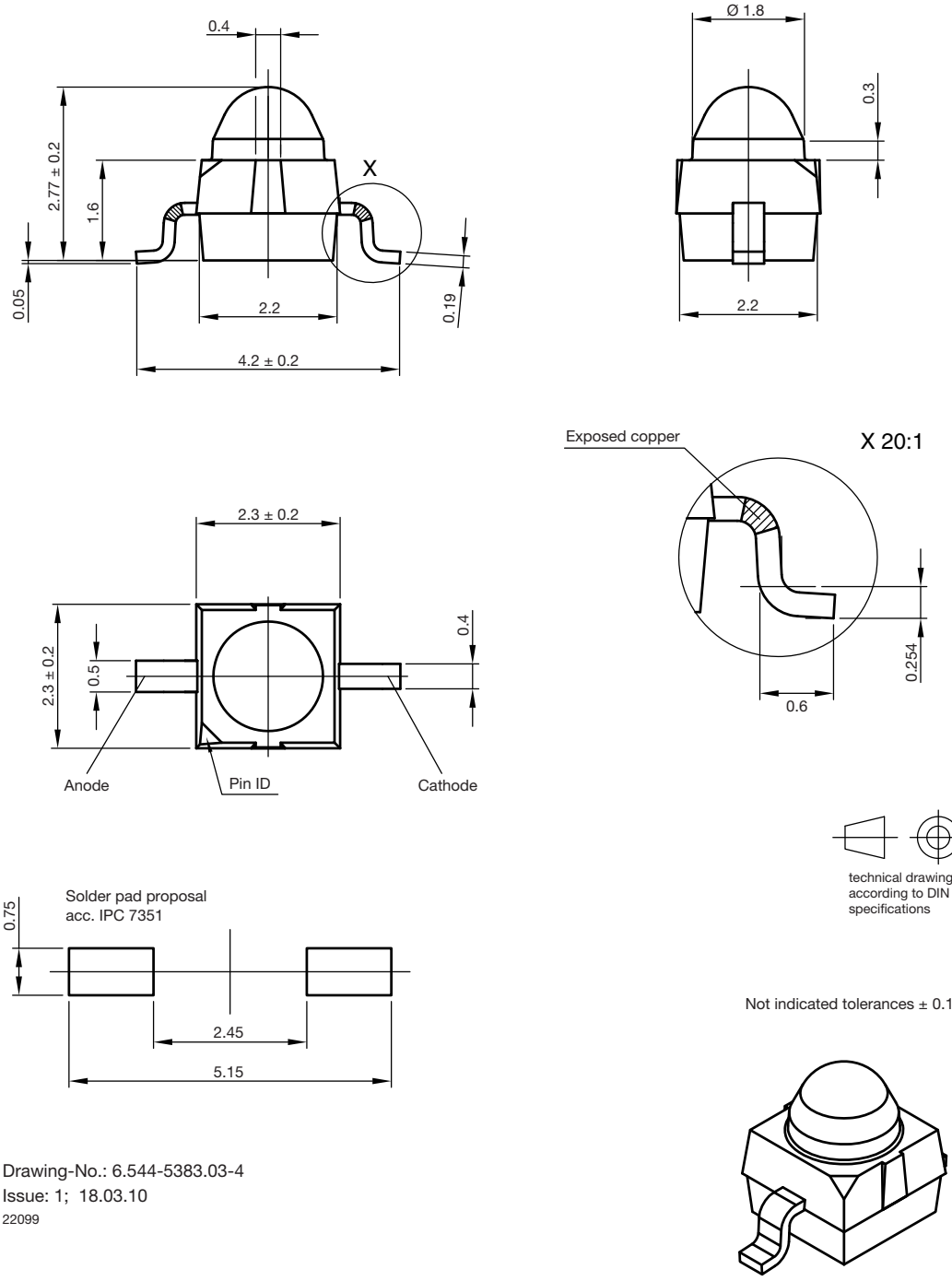
In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), RH < 5 %.

**PACKAGE DIMENISONS** in millimeters: **VSMY2850RGX01**




Drawing-No.: 6.544-5391.03-4
Issue: 1; 18.03.10
22100

**PACKAGE DIMENSIONS** in millimeters: **VSMY2850GX01**

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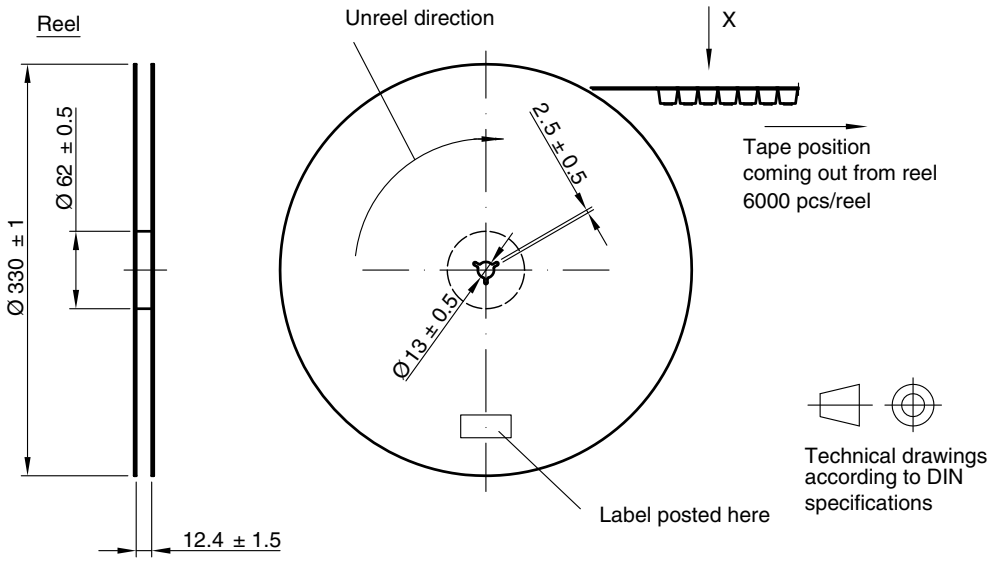
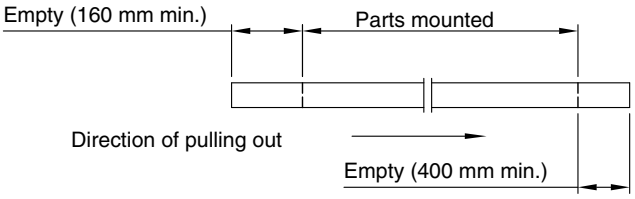
Issue: 1; 18.03.10
22099

## **TAPING AND REEL DIMENSIONS** in millimeters: **VSMY2850RGX01**

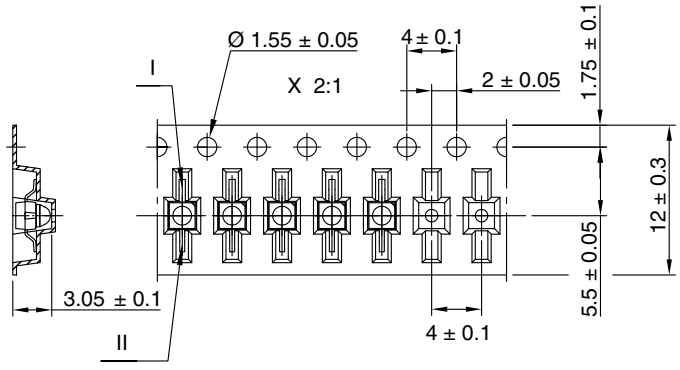



Leader and trailer tape:



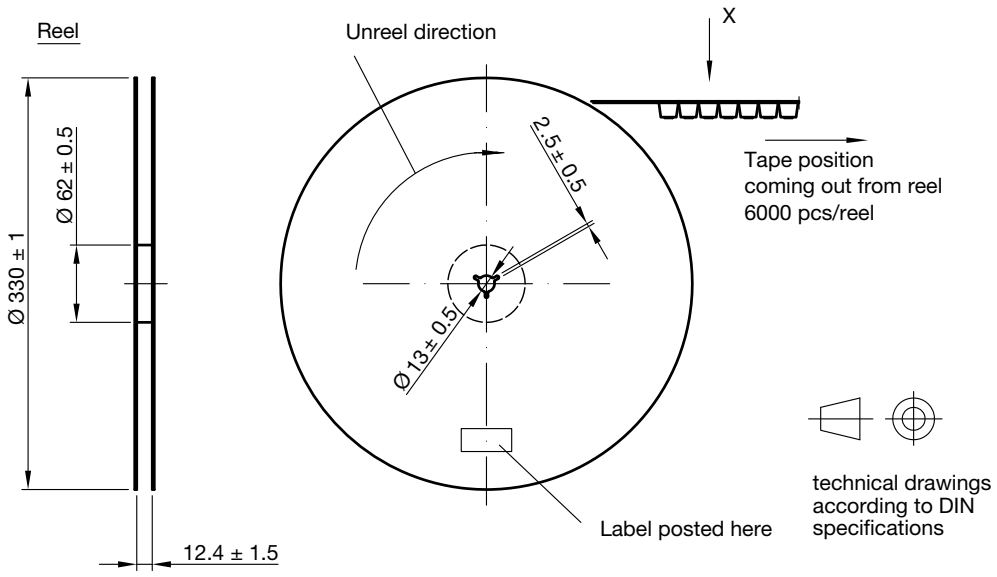

Terminal position in tape

| Device | Lead I | Lead II |
|---|---|---|
| VEMT2000 | Collector | Emitter |
| VEMT2500 | | |
| VEMD2000 | Cathode | Anode |
| VEMD2500 | | |
| VSMB2000 | | |
| VSMG2000 | | |
| VSMY2850RG | Anode | Cathode |

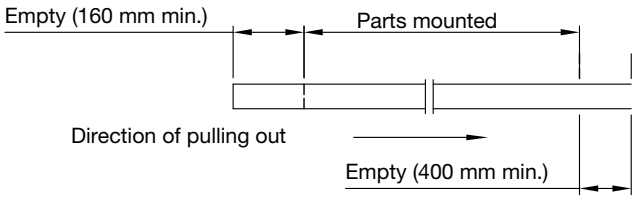



Drawing-No.: 9.800-5100.01-4
Issue: 2; 18.03.10
21572

## **TAPING AND REEL DIMENSIONS** in millimeters: **VSMY2850GX01**

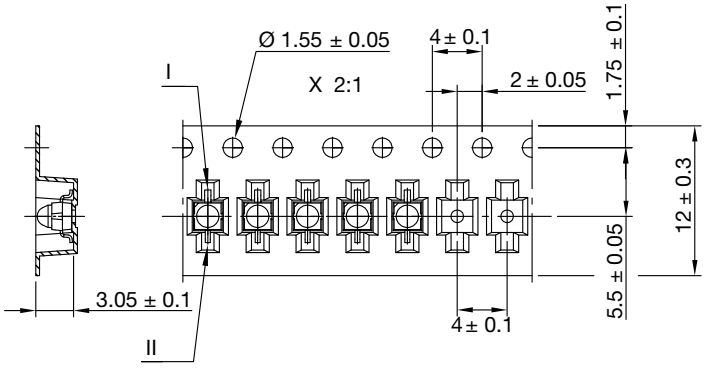



Leader and trailer tape:




Terminal position in tape

| Device | Lead I | Lead II |
|---|---|---|
| VEMT2020 | Collector | Emitter |
| VEMT2520 | | |
| VSMB2020 | Cathode | Anode |
| VSMG2020 | | |
| VEMD2020 | | |
| VEMD2520 | | |
| VSMY2850G | Anode | Cathode |
| VSMB294008GC | | |




Drawing-No.: 9.800-5091.01-4
Issue: 3; 18.03.10

21571

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